

# STAUF

— seit 1828 —



## STAUF XP 10

Levelling compound under elastic and textile floorings



### Technical Datasheet

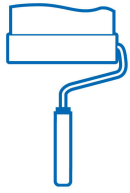
|  |   |
|--|---|
| Product number   | ✓ 133040  |
| Special features                                       | ✓ self-levelling<br>✓ very easy to sand<br>✓ Low-stress   |
| Application range                                      | ✓ suitable below elastic/textile floor coverings and multi layer wood flooring  |
| Suitable subfloors                                     | ✓ sanded mastic asphalt screed<br>✓ concrete C 25 / 30 according to DIN 1045 (non-skid surface)<br>✓ calcium sulphate (flow) floors<br>✓ STAUF levelling compounds<br>✓ magnesite and plaster floors<br>✓ unlaminated gypsum fibre boards<br>✓ cement floors<br>✓ cavity floors |
| Suitable primers                                       | ✓ STAUF VDP 130<br>✓ STAUF VPU 155 S + STAUF quartz sand<br>✓ STAUF D 54<br>✓ STAUF VDP 160<br>✓ STAUF VEP 195 + STAUF quartz sand<br>✓ STAUF WEP 180 + STAUF quartz sand   |
| Product properties                                     | ✓ up to 1 mm suitable for castors swivel chairs according to DIN EN 12529<br>✓ pumpable<br>✓ self-levelling   |
| Color  | ✓ light grey  |
| Consumption in g/m <sup>2</sup> per mm layer thickness | ✓ 1500g per mm layer thickness  |
| Accessibility/ready for foot traffic                   | ✓ after 3 hours at 20 °C, max 65% rel. humidity   |

|                           |   |
|---------------------------|---|
| Ready for installation    | <ul style="list-style-type: none"> <li>✓ 24 hours at 20 °C, (with 3 mm layer thickness) max 65% rel. humidity</li> <li>✓ 48 hours (for 5 mm layer thickness) at 20°C, relative humidity 65% max.</li> <li>✓ 72 hours (for 5 - 10 mm layer thickness) at 20°C, relative humidity 65% max.</li> </ul> |
| Additional instructions 1 | <ul style="list-style-type: none"> <li>✓ Without flammable components in accordance with DIN 4102: A1 and DIN EN 13501: A1fl.</li> <li>✓ Under multi-layer wood flooring, at least 3 mm thick layer and if bonded with elastic or hard elastic STAUF wood flooring adhesives</li> </ul>             |
| Room climate at work site | <ul style="list-style-type: none"> <li>✓ Minimum 18 °C, maximum 75% rel. humidity, preferably max. 65%</li> </ul>   |
| Transport requirements    | <ul style="list-style-type: none"> <li>✓ dry</li> </ul>   |
| Storage requirements      | <ul style="list-style-type: none"> <li>✓ dry</li> <li>✓ cool</li> </ul>   |
| Shelf-life                | <ul style="list-style-type: none"> <li>✓ 9 months</li> </ul>  |
| Giscode                   | <ul style="list-style-type: none"> <li>✓ ZP1</li> </ul>   |
| Emicode                   | <ul style="list-style-type: none"> <li>✓ EC1 plus</li> </ul>  |
| Available packaging       | <ul style="list-style-type: none"> <li>✓ 25 kg paper bag</li> </ul>   |
| layer thickness           | <ul style="list-style-type: none"> <li>✓ for wood flooring minimum 3 mm</li> <li>✓ 1–10 mm</li> <li>✓ At least 2 mm under flexible floor coverings</li> <li>✓ At least 1 mm under textile floor coverings</li> <li>✓ mastic asphalt screed 2-5 mm</li> </ul>  |
| Processing time           | <ul style="list-style-type: none"> <li>✓ approx. 30 minutes at 20 °C and 65% rel. humidity</li> </ul>   |
| Mixing ratio component A  | <ul style="list-style-type: none"> <li>✓ 25 kg levelling compound</li> </ul>  |
| Mixing ratio component B  | <ul style="list-style-type: none"> <li>✓ 6 liter water</li> </ul>   |



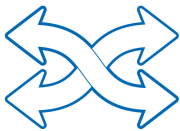
## EXAMINATION OF SUBFLOOR

Before laying the covering, check the substrate in accordance with DIN 18356 and DIN 18365. The subfloor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of from contaminants that may prevent adhesion, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorption of subfloors as well as temperature, air humidity and subfloor temperature.



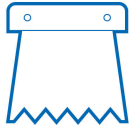
## SUBFLOOR PREPARATION

It must be ensured that the subfloor is ready for installation by performing proper subfloor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of subfloor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF repair resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. In order to improve adhesion of adhesives and leveling compounds, prime the subfloor with the appropriate primer.



## MIXING PROCEDURE OF COMPONENTS

Add specified amount of water (clean and cold) into clean mixing bucket. Add complete content of container and stir evenly. For mixing, use an electrical stirrer with approx. 600 - 800 rpm with spiral or large paddle mixer. Mix until you have a homogeneous compound. Mix for another two minutes, wait one minute and then stir again for one minute (does NOT apply for non-self levelling compounds).



## PROCESSING

Apply self-levelling compound within specified processing time. Do not pour the compound from mixing beaker on one spot only, but spread over a surface of approx. 2 x 2 m by changing position during pouring. Layer thickness can be controlled by using a wiper or a smoothing trowel. Air the levelling compound using a prickler roller. Self-levelling compounds do not require any additional mechanical spreading and form an even surface by themselves. Lower temperatures or higher ambient humidity delay the period until floor is ready for installation. The compound sets hydraulically, which means that it needs to be protected from direct sunlight and draughts. Before applying a further layer of filler or levelling compound, apply an intermediate layer of STAUF dispersion primer for filler compounds. Do not prime levelling and filler compounds before direct adhesion. The maximum specified layer thickness must not be exceeded when applying two coats of trowel. The thickness of the second coat must not be higher than that of the first coat. For chipboard and OS panels, layer thicknesses of up to 5 mm are admissible. On less absorbent substrates and under flexible coverings, layer thickness of at least 2 mm. Best for use at 18 - 25 °C, substrate temperature between 15 - 23 °C (with underfloor heating 18 - 22 °C) and relative humidity below 65 %, until the adhesive has set. Processing can also be carried out using a suitable mixing pump. If work is interrupted, the mixing pump and hoses must be washed out.



## LIMITATION OF LIABILITY

The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior on-site testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

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